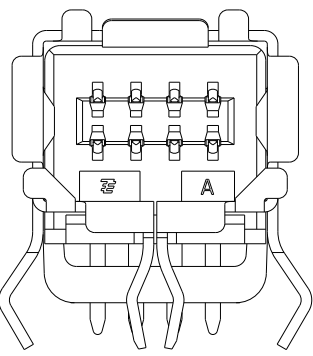
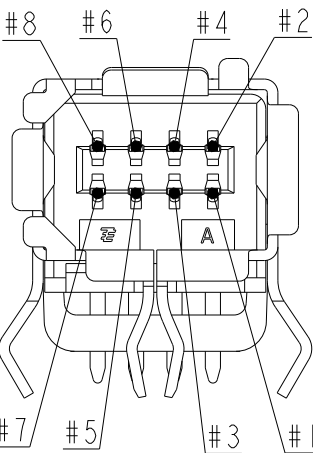
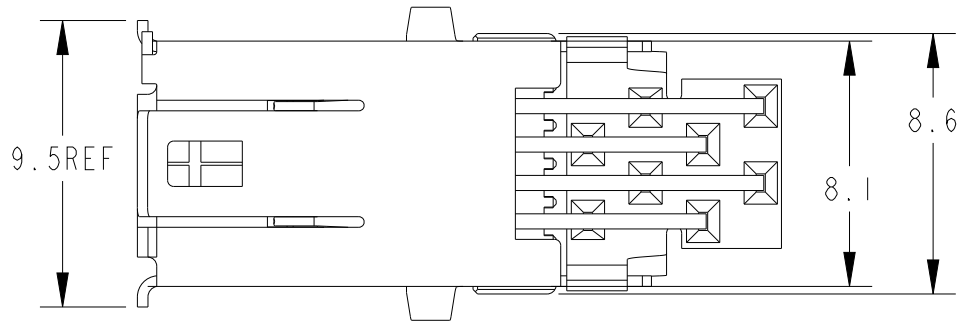


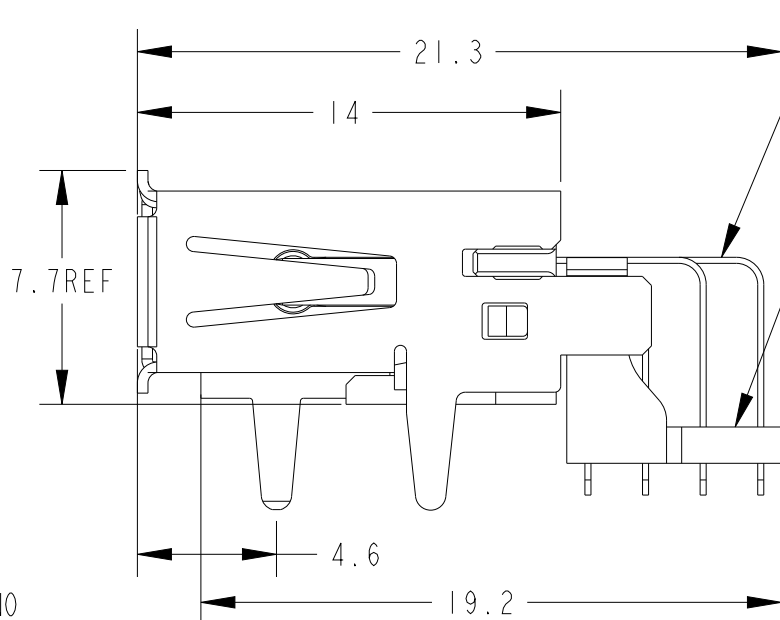
P	LTR	DESCRIPTION	DATE	DWN	APVD
A		RELEASED	14JUL2008	M.M	I.H
AI		SUPERSEDED_PCN-21-114977	02DEC2021	SS	PJ
F		ALIGNING THE REVISION TO MATCH ACTUAL PART AND TCPN REV	05MAY2026	HS	SK



1-2040537-1

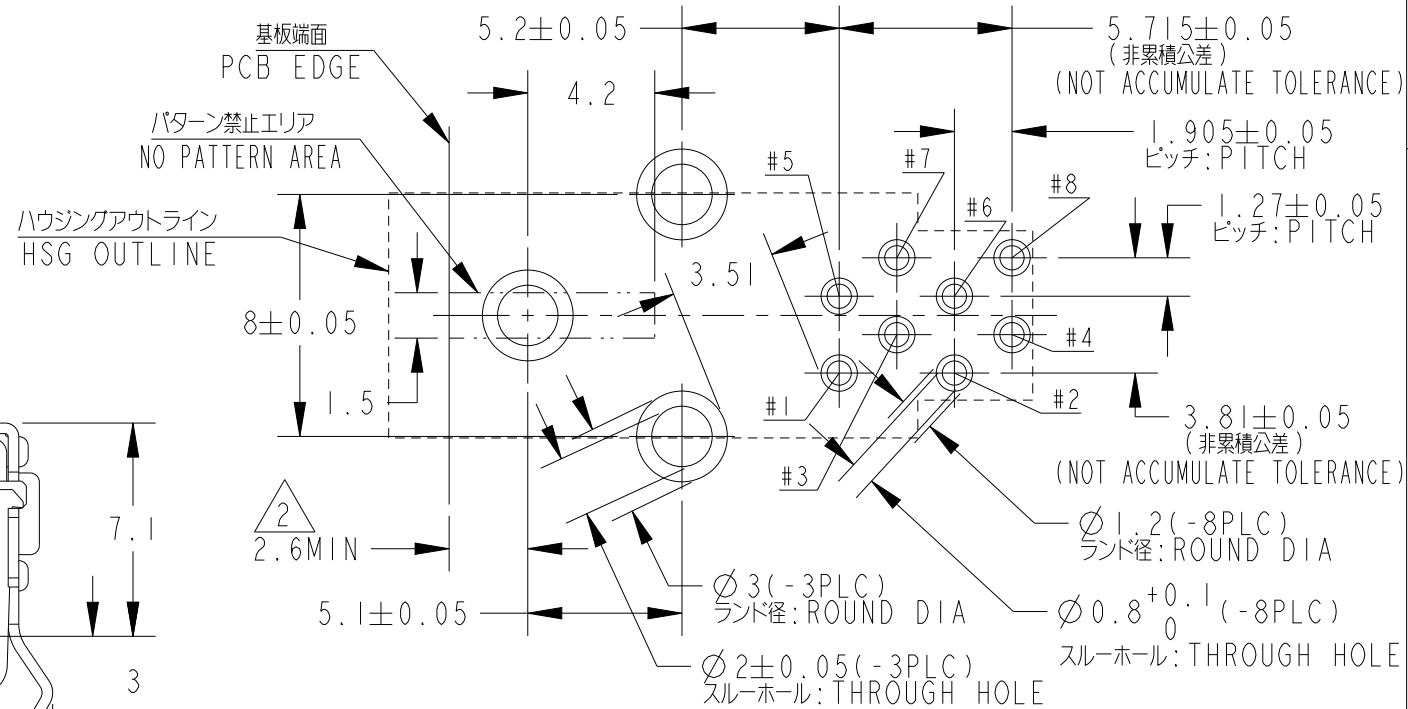
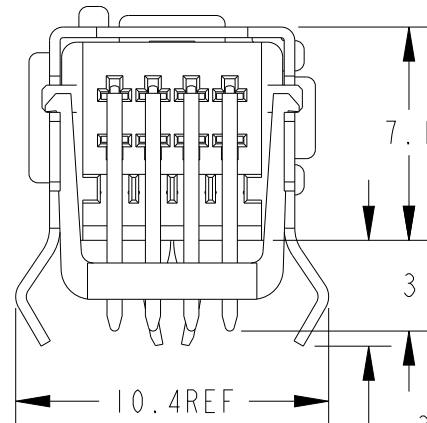


回路番号
CIRCUIT NO

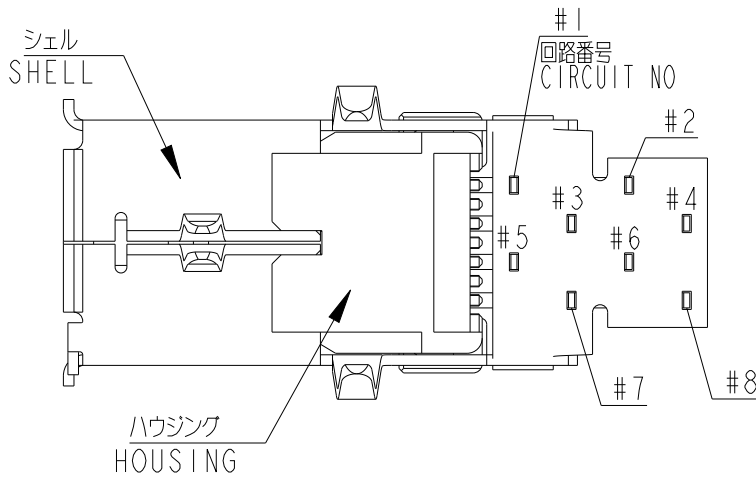


コンタクト
CONTACT

タインプレート
TINE PLATE



推奨基板寸法 (実装面側) ± 1.6
RECOMMENDED BOARD DIMENSION
(CONNECTOR SIDE) ± 1.6



1. MATERIAL AND FINISH
CONTACT
COPPER ALLOY
UNDER ALL SURFACE NICKEL 1.27 μ m MIN
TOP CONTACT AREA : GOLD 0.5 μ m MIN
SOLDERING AREA : TIN PLATE
HOUSING
THERMO PLASTIC (UL94V-0)
SHELL
COPPER ALLOY
UNDER ALL SURFACE NICKEL
TOP ALL SURFACE TIN

1. 材料及び仕上げ
コンタクト
材料: 銅合金
全面ニッケル下地めっき 1.27 μ m MIN
接点部: 金めっき 0.5 μ m MIN
半田付け部: 錫めっき
ハウジング
材料: 熱可塑性樹脂 (難燃性 UL94V-0)
シェル
材料: 銅合金
全面ニッケル下地めっき
全面錫めっき

2. DIMENSION DECIDED BY CUSTOMER.

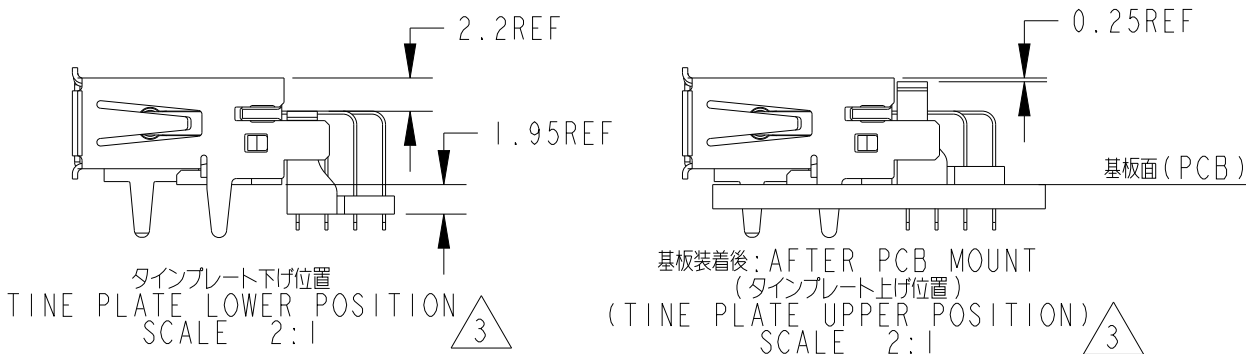
2. 顧客決定寸法

3. TINE PLATE CAN MOVE UP AND DOWN.

3. タインプレートは可動式

AS SHOWN AS : 2040537-1

8	D-SHAPE TYPE-II	1-2040537-1
8	D-SHAPE TYPE-I	2040537-1
POS	DESCRIPTION	PART NO



タインプレート下げ位置
TINE PLATE LOWER POSITION
SCALE 2:1

基板装着後: AFTER PCB MOUNT
(タインプレート上げ位置)
(TINE PLATE UPPER POSITION)
SCALE 2:1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: 単位: 耗 mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:
	一般公差 $\pm 0.3, \pm 5^\circ$
	0-PLC $\pm$
	1-PLC $\pm$
	2-PLC $\pm$
	3-PLC $\pm$
	4-PLC $\pm$
	ANGLES $\pm$
MATERIAL 材料	FINISH 仕上

DWN	14JUL2008
CHK	M. MAEBASHI
	14JUL2008
APVD	I. HASEGAWA
	14JUL2008
PRODUCT SPEC	108-78405
APPLICATION SPEC	-
WEIGHT	-
CUSTOMER DRAWING	

TE Connectivity			
INDUSTRIAL MINI I/O CONN 1.27mm PITCH HDR ASSY (DIP/H-TYPE) 8POS			
SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	00779	C-2040537	-
SCALE 尺度 4:1		SHEET 1 OF 1	REV F